INTEGRATED CIRCUITS



Product specification Supersedes data of 1996 Jun 06 IC24 Data Handbook

1998 May 20



HILIP

74LVC273

FEATURES

- Wide supply voltage range of 1.2V to 3.6V
- Conforms to JEDEC standard 8-1A
- Inputs accept voltages up to 5.5V
- CMOS low power consumption
- Direct interface with TTL levels
- Output drive capability 50Ω transmission lines @ 85°C

DESCRIPTION

The 74LVC273 is a low-voltage Si-gate CMOS device, superior to most advanced CMOS compatible TTL families.

The 74LVC273 has eight edge-triggered , D-type flip-flops with individual D inputs and Q outputs. The common clock (CP) and master reset (MR) inputs load and reset (clear) all flip-flops simultaneously. The state of each D input, one set-up time before the LOW-to-HIGH clock transition, is transferred to the corresponding output (Qn) of the flip-flop.

All outputs will be forced LOW independently of clock or data inputs by a LOW voltage level on the \overline{MR} input.

The device is useful for applications where the true output only is required and the clock and master reset are common to all storage elements.

QUICK REFERENCE DATA

GND = 0V; $T_{amb} = 25^{\circ}C$; $t_r = t_f \le 2.5$ ns

SYMBOL PARAMETER		CONDITIONS	TYPICAL	UNIT	
t _{PHL} /t _{PLH}	Propagation delay CP to Qn; MR to Q _n	C _L = 50pF V _{CC} = 3.3V	6.0 6.0	ns	
f _{max}	Maximum clock frequency		230	MHz	
C _I Input capacitance			5.0	pF	
C _{PD} Power dissipation capacitance per flip-flop		$V_1 = GND \text{ to } V_{CC}^1$	22	pF	

NOTE:

CPD is used to determine the dynamic power dissipation (P_D in μ W) P_D = C_{PD} × V_{CC}² x f_i + Σ (C_L × V_{CC}² × f_o) where: f_i = input frequency in MHz; C_L = output load capacity in pF; f_o = output frequency in MHz; V_{CC} = supply voltage in V; Σ (C_L × V_{CC}² × f_o) = sum of the outputs. 1

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
20-Pin Plastic SO	–40°C to +85°C	74LVC273 D	74LVC273 D	SOT163-1
20-Pin Plastic SSOP Type II	–40°C to +85°C	74LVC273 DB	74LVC273 DB	SOT339-1
20-Pin Plastic TSSOP Type I	-40°C to +85°C	74LVC273 PW	74LVC273PW DH	SOT360-1

PIN CONFIGURATION

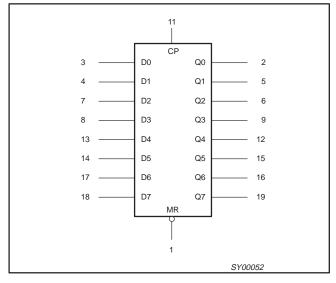
MR 1				
Q0 2	19 Q7			
D0 3	18 D7			
D1 4	17 D6			
Q1 5	16 Q6			
Q2 6	15 Q5			
D2 7	14 D5			
D3 8	13 D4			
Q3 9	12 Q4			
GND 10	11 CP			
SY00051				

PIN DESCRIPTION

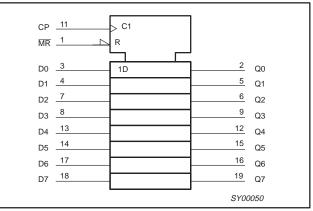
PIN NUMBER	SYMBOL	FUNCTION
1	MR	Master reset input (active LOW)
2, 5, 6, 9, 12, 15, 16, 19	Q0 – Q7	Flip-flop outputs
3, 4, 7, 8, 13, 14, 17, 18	D0 – D7	Data inputs
10	GND	Ground (0V)
11	СР	Clock input (LOW-to-HIGH, edge-triggered)
20	V _{CC}	Positive power supply

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LOGIC SYMBOL



IEEE/IEC LOGIC SYMBOL



FUNCTION TABLE

OPERATING		INPUTS		OUTPUT
MODES	MR	СР	Dn	Q0 – Q7
Reset (clear)	L	Х	Х	L
Load '1'	Н	Î	h	Н
Load '0'	Н	Î	Ι	L

H = HIGH voltage level
h = HIGH voltage level one set-up time prior to the HIGH-to-LOW CP transition

LOW voltage level =

LOW voltage level one set-up time prior to the HIGH-to-LOW CP transition =

LOW-to-HIGH transition =

Х = Don't care

L

Т

↑

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	LIM	UNIT	
STMBOL	FARAIVETER	CONDITIONS	MIN	MAX	UNIT
N	DC supply voltage (for max. speed performance)		2.7	3.6	V
V _{CC}	DC supply voltage (for low-voltage applications)			3.6	V
VI	DC Input voltage range		0	5.5	V
V _{I/O}	DC Input voltage range for I/Os		0	V _{CC}	V
Vo	DC output voltage range		0	V _{CC}	V
T _{amb}	Operating free-air temperature range		-40	+85	°C
t _r , t _f	Input rise and fall times	$V_{CC} = 1.2 \text{ to } 2.7 \text{V}$ $V_{CC} = 2.7 \text{ to } 3.6 \text{V}$	0 0	20 10	ns/V

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ABSOLUTE MAXIMUM RATINGS¹

In accordance with the Absolute Maximum Rating System (IEC 134) Voltages are referenced to GND (ground = 0V)

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +6.5	V
I _{IK}	DC input diode current	V ₁ < 0	-50	mA
VI	DC input voltage	Note 2	-0.5 to +5.5	V
I _{OK}	DC output diode current	$V_{O} > V_{CC} \text{ or } V_{O} < 0$	± 50	mA
V _O	DC output voltage	Note 2	–0.5 to V _{CC} +0.5	V
Ι _Ο	DC output source or sink current	$V_{O} = 0$ to V_{CC}	±50	mA
I _{GND} , I _{CC}	DC V _{CC} or GND current		±100	mA
T _{stg}	Storage temperature range		-65 to +150	°C
PTOT plastic shrink mini-pack (SSOP and		above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	500 500	mW

NOTES:

1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

2. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions voltages are referenced to GND (ground = 0V)

			L	UNIT				
SYMBOL	PARAMETER	TEST CONDITIONS	Temp = -					
			MIN	TYP ¹	MAX	1		
M		$V_{CC} = 1.2V$	V _{CC}			V		
V _{IH}	HIGH level Input voltage	$V_{CC} = 2.7 \text{ to } 3.6 \text{V}$	2.0			1 [×]		
M		$V_{CC} = 1.2V$			GND			
V_{IL}	LOW level Input voltage	$V_{CC} = 2.7 \text{ to } 3.6 \text{V}$			0.8			
	HIGH level output voltage	$V_{CC} = 2.7 V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = -12 mA$	V _{CC} -0.5					
		$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = -100\mu A$	V _{CC} -0.2	V _{CC}		V		
V _{OH}		$V_{CC} = 3.0V$; $V_I = V_{IH}$ or $V_{IL;} I_O = -12mA$	V _{CC} -0.6			1		
		$V_{CC} = 3.0V$; $V_I = V_{IH}$ or $V_{IL;} I_O = -24mA$	V _{CC} -1.0					
		$V_{CC} = 2.7 V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = 12 mA$			0.40			
V _{OL}	LOW level output voltage	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu A$			0.20	V		
		$V_{CC} = 3.0V$; $V_I = V_{IH}$ or $V_{IL;} I_O = 24mA$			0.55	1		
t _l	Input leakage current	$V_{CC} = 3.6V; V_1 = 5.5V \text{ or GND}$		±0.1	±5	μA		
I _{OZ}	3-State output OFF-state current	$V_{CC} = 3.6V$; $V_I = V_{IH}$ or V_{IL} ; $V_O = V_{CC}$ or GND		0.1	±10	μA		
I _{CC}	Quiescent supply current	$V_{CC} = 3.6V; V_I = V_{CC} \text{ or GND}; I_O = 0$		0.1	10	μA		
ΔI_{CC}	Additional quiescent supply current	$V_{CC} = 2.7V$ to 3.6V; $V_1 = V_{CC} - 0.6V$; $I_0 = 0$		5	500	μA		

NOTE:

1. All typical values are at V_{CC} = 3.3V and T_{amb} = 25°C.

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AC CHARACTERISTICS

GND = 0V; $t_R = t_F = 2.5ns$; $C_L = 50pF$; $R_L = 500\Omega$; $T_{amb} = -40^{\circ}C$ to +85°C.

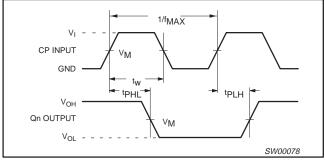
					LIM	ITS			
SYMBOL	PARAMETER	WAVEFORM	Vcc	V _{CC} = 3.3V ±0.3V			V _{CC} = 2.7V		
			MIN	TYP ¹	MAX	MIN	ТҮР	MAX	1
t _{PHL} t _{PLH}	Propagation delay CP to Qn	1		6.0	10.2		6.6	11.2	ns
t _{PHL}	Propagation delay MR to Qn	2		6.3	11.0		7.4	12.0	ns
t _W	Clock pulse width HIGH or LOW	1	4	1.2		5	1.8		ns
t _W	Master reset pulse width LOW	2	4	1.2		5	1.7		ns
t _{rem}	Removal time MR to CP	2	2	-1.0		3	-1.0		ns
t _{su}	Set-up time D _n to CP	3	2	0.7		3	1.0		ns
t _h	Hold time D _n to CP	3	0	-0.6		0	-0.9		ns
f _{max}	Maximum clock pulse frequency	1	125			100			MHz

NOTE:

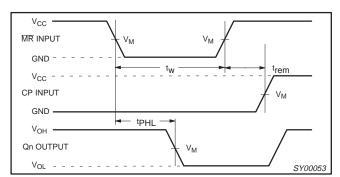
1. These typical values are at V_{CC} = 3.3V and T_{amb} = 25°C.

AC WAVEFORMS

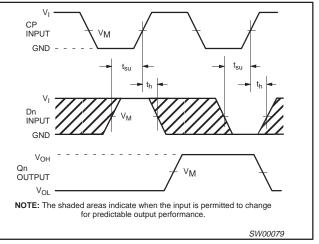
 V_M = 1.5V at $V_{CC} \ge$ 2.7V. V_M = 0.5 V_{CC} at $V_{CC} <$ 2.7V. V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load.



Waveform 1. Clock (CP) to output (Q_n) propagation delays, the clock pulse width and the maximum clock pulse frequency



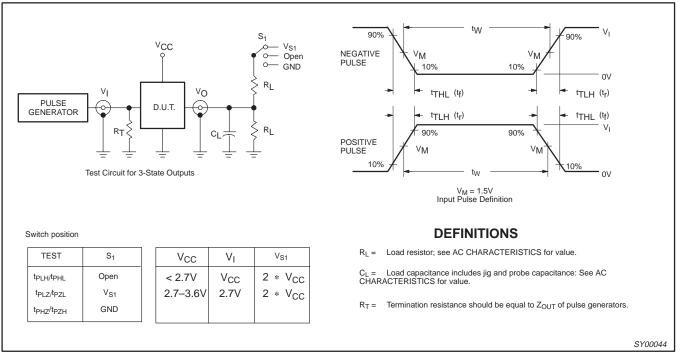
Waveform 2. Master reset (MR) pulse width, the master reset to output (Qn) propagation delays and the master reset to clock (CP) removal time



Waveform 3. Data set-up and hold times for the data input (D_n)

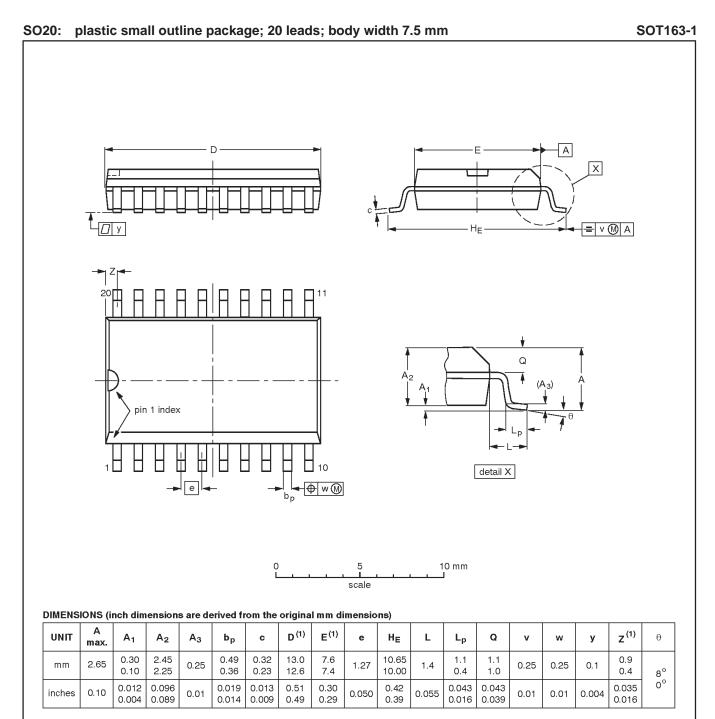
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TEST CIRCUIT



Waveform 4. Load circuitry for switching times

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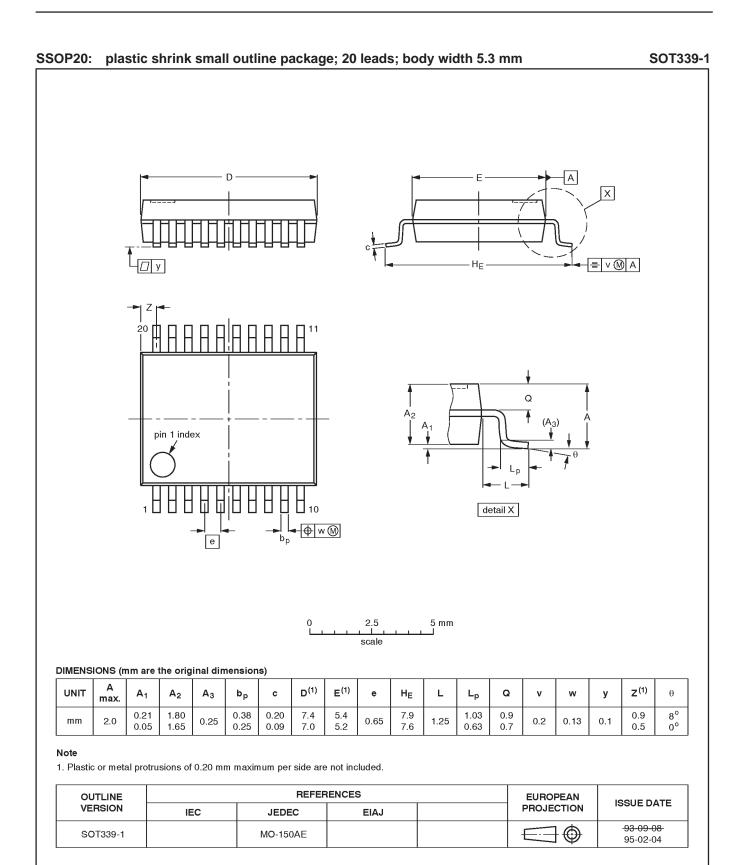


Note

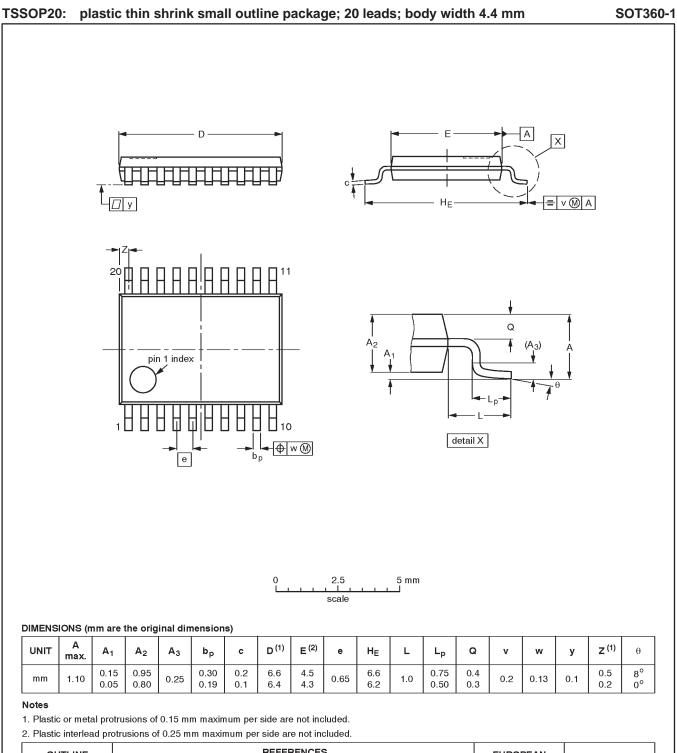
1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFERENCES			EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT163-1	075E04	MS-013AC				-92-11-17 95-01-24	

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OUTLINE REFERENCES				EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT360-1		MO-153AC				-93-06-16 95-02-04

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DEFINITIONS				
Data Sheet Identification Product Status Definition		Definition		
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.		
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> print code Document order number:

Date of release: 05-96 9397-750-04505

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